Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832
Email & Skype: info@chipsmall.com Web: www.chipsmall.com
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China

Non-Silicone Heat Transfer Compound

8610

BUY NOW

- Special synthetic base, fortified with metal oxides and compounded to a paste-like consistency for ease of application
- High efficient thermal conductive properties
  - Means more rapid transfer of heat for longer component life
- High temperature stability
  - Provides physical properties of low bleed and low evaporation for long-term service in any application that requires Heat Sink Compound.
- Uses synthetic fluids and metal oxide fillers
  - Provides excellent conductive properties that exceed those of other heat sink formulas
- Will not dry, harden, melt or migrate in any heat sink application
- Compatible with metal and plastic components
- Also available in a silicone version

Benefits of Non Silicone Heat Transfer Compound OVER Silicone

No migration and component contamination.

Applications

- Typically, Heat Transfer Compounds (heat sink compounds) are used in OEM Electronic Component Plants to insure fast, accurate heat transfer in electronic components and circuitry
- Other used:
  - Semiconductor Mounting Devices
  - Thermal joints
  - Ballast heat transfer mediums
  - Power resistor mountings
  - Thermocouple wells
  - Transistor diodes & silicone rectifier base and mounting studs
  - ALL electric and electronic devices where efficient heat transfer cooling through thermal coupling is required

Specifications

Physical Properties	Test Method	Non Silicone 8610	Silicone 860
Appearance	Visual	Off white / smooth paste	White paste
Consistency	ASTM D 217	310-320	
Specific Gravity @ 25°C (77°F)		2.5 min	2.3 min
Bleed % 24 hours @ 200°C	FTM-321	1.0% max	2.0% max
Evaporation 24 hours @ 200°C	FTM-321	2.0% max	2.0% max
Dropping Point	ASTM D-566	> 500°F (260°C)	> 500°F (260°C)
Min. operating temp.		-40°F/-40°F	55°F/48°C
Max. operating temp.		200°C	200°C (consistent) 300°C (intermittent)

Electrical Properties	Test Method	Non Silicone 8610	Silicone 860
Thermal Conductivity	Hot Wire Method Heat Flow #36 °C	0.773 W/m•K	0.657 W/m•K
Dielectric Strength (0.05l gap)	ASTM D-149	350 V/MIL	400 V/MIL
Dielectric Constant @ 1000 Hz	ASTM D- 150	4.4	3.81
Dissipation Factor @ 1000 Hz	ASTM D 150	0.0021	0.0032
Resistivity @ 21°C	ASTM D 150	6.38×10^{13} Ohm•cm	1.5×10^{15} Ohm•cm

Available Sizes

Catalog Number	Sizes Available	Description
8610-60G	60g (2 oz)	Liquid - TUBE
8610-1P	1 pint (2.5 lbs)	Tub

© 2000 - 2010 MG Chemicals. All rights reserved. Site Map Terms & Conditions Contact Us